



General Description

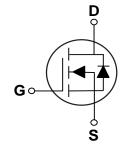
The TNMNC033 is the high cell density trenched N-ch MOSFETs, which provides excellent R_{DSON} and efficiency for most of the small power switching and load switch applications.

The TNMNC033 meets the RoHS and Green Product requirement with full function reliability approved.

BV _{DSS}	R _{DS(ON)}	I_D
30 V	33 mΩ	4.6 A

SOT-23 Pin Configuration





Features

- 30V, 4.6A, $R_{DS(ON)}$ =33m Ω @ V_{GS} =10V
- · Green Device Available
- · Super Low Gate Charge
- · Excellent Cdv/dt effect decline
- · Advanced high cell density Trench technology

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
	Drain Current - Continuous, V _{GS} @ 10V (NOTE 1) (T _A =25°C)	4.6	Α
I _D	Drain Current - Continuous, V _{GS} @ 10V (NOTE 1) (T _A =70°C)	3.7	Α
I_{DM}	Drain Current - Pulsed (NOTE 2)	18.4	Α
P_D	Total Power Dissipation (NOTE 3) (T _A =25°C)	1	W
T_J	Operating Junction Temperature Range	-50 to 150	°C
T_{STG}	Storage Temperature Range	-50 to 150	°C
larking Code		AC	

Thermal Characteristics					
Symbol	Parameter	Тур.	Max	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (NOTE 1)		125	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case (NOTE 1)		80	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	30			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =25°C			1	uA
	Diam-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I RDOVONI)	Static Drain-Source On-Resistance	V_{GS} =10V , I_D =4A		27	33	mΩ
	(NOTE 2)	V _{GS} =4.5V , I _D =3A		36	50	11122
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0	1.5	2.5	V
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =4A		7		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			5.0	6.9	
Q_{gs}	Gate-Source Charge	V_{DS} =15V , V_{GS} =4.5V , I_{D} =4A		1.1	2.2	nC
Q_{gd}	Gate-Drain Charge			2.6	2.8	
$T_{d(on)}$	Turn-On Delay Time			2	4	
T _r	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		34.4	62	no
$T_{d(off)}$	Turn-Off Delay Time	, I _D =4A		13.2	26	ns
T_f	Fall Time			4.8	9.6	
C _{iss}	Input Capacitance			420	582	
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , F=1MHz		60	87	pF
C _{rss}	Reverse Transfer Capacitance			53	71	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current (NOTE 1 \ 4)	V _G =V _D =0V,Force Current			4.6	Α
I _{SM}	Pulsed Source Current (NOTE 2 \ 4)				18.4	Α
V_{SD}	Diode Forward Voltage (NOTE 2)	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1.2	V
t _{rr}	Reverse Recovery Time	I _F =4A , dl/dt=100A/us , T _J =25°C		8.7		ns
Q_{rr}	Reverse Recovery Charge			2.3		nC

NOTES:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2oz copper.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. The power dissipation is limited by 150 $\!\!\!\!^{\circ}_{\circ}$ junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.





Characteristics Curves

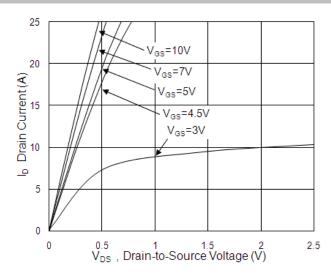


Fig.1 Typical Output Characteristics

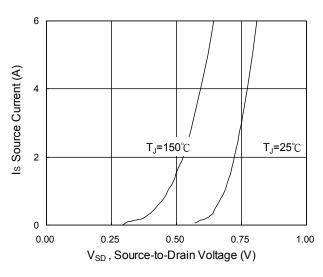


Fig.3 Forward Characteristics Of Reverse

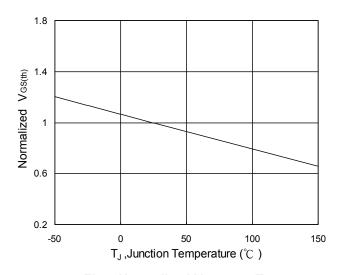


Fig.5 Normalized V_{GS(th)} vs. T_J

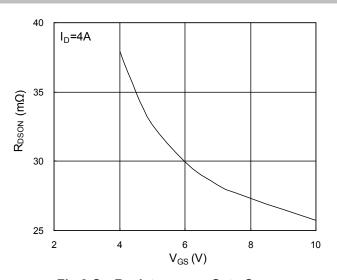


Fig.2 On-Resistance vs. Gate-Source

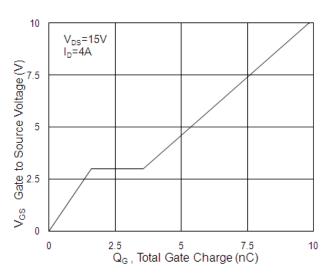


Fig.4 Gate-Charge Characteristics

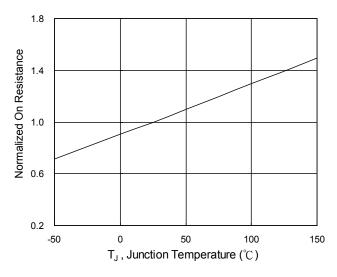
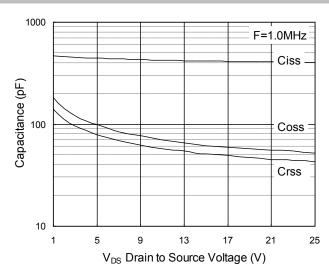


Fig.6 Normalized R_{DSON} vs. T_J





Characteristics Curves



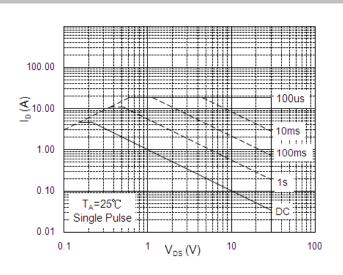


Fig.7 Capacitance

Fig.8 Safe Operating Area

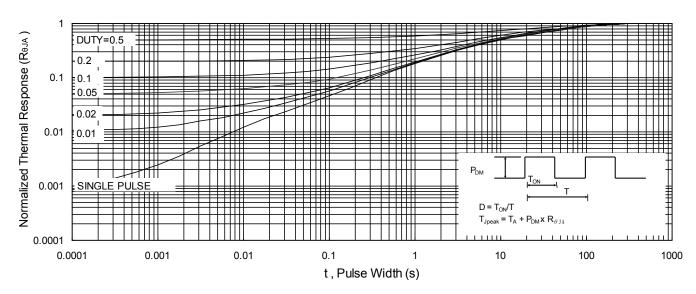


Fig.9 Normalized Maximum Transient Thermal Impedance

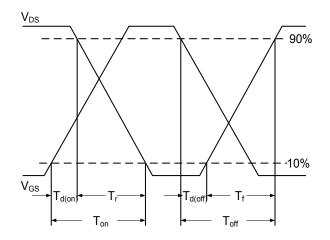


Fig.10 Switching Time Waveform

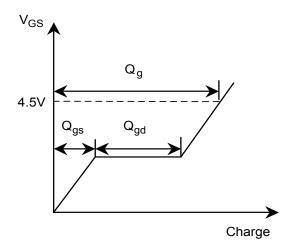
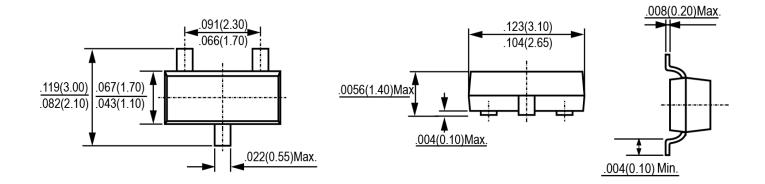


Fig.11 Gate Charge Waveform





Package Outline Dimensions



SOT-23Dimensions in inches and (millimeters)





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